



Material Content Data Sheet



Sales Product Name				IPD80R1K4CE		Issued		27. September 2017	
MA#				MA001133458					
Package				PG-TO252-3-313		Weight*		319.29 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.894	1.22	1.22	12194	12194	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		461		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		138		
	non noble metal	copper	7440-50-8	147.096	46.07	46.13	460693	461292	
wire	non noble metal	aluminium	7429-90-5	0.525	0.16	0.16	1644	1644	
encapsulation	organic material	carbon black	1333-86-4	1.399	0.44		4381		
	plastics	epoxy resin	-	24.478	7.67		76662		
	inorganic material	silicondioxide	60676-86-0	113.996	35.70	43.81	357027	438070	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11714	11714	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4449	4460	
solder	noble metal	silver	7440-22-4	0.084	0.03		262		
	non noble metal	tin	7440-31-5	0.067	0.02		210		
	non noble metal	lead	7439-92-1	3.198	1.00	1.05	10014	10486	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.01	6.02	60062	60140	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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